

# DATASHEET

# Luminosity • White Color LED EAPL3232WA0



#### **Features**

- Super luminosity white LED.
- White SMT package.
- Built in 3 LED chips.
- Lead frame package with individual 6 pins.
- · Wide viewing angle.
- Soldering methods: Reflow soldering.
- High performance.
- Pb-free.
- The product itself will remain within RoHS compliant version.

## **Descriptions**

Due to the package design, EAPL3232WA0 has wide viewing angle, low power consumption and high luminous intensity. This feature makes it ideal for light pipe or lighting application.

#### **Applications**

- Amusement equipment.
- Information boards.
- Flashlight for digital camera of cellular phone.
- Lighting for small size device.



# **Device Selection Guide**

Chip	F ** 101	Resin Color	
Material	Emitted Color		
InGaN	White	Water Clear	

# **Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Rating	Unit	
Reverse Voltage*1	$V_R$	5	V	
Peak Forward Current (Duty 1/10 @1KHz) *1	${ m I}_{ m FP}$	100	mA	
Forward Current*1	$I_F$	25	mA	
Power Dissipation*1	Pd	100	mW	
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\!\mathbb{C}$	
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\!\mathbb{C}$	
Electrostatic Discharge(HBM) *1	ESD	150	V	
Soldering Temperature	Tsol	Reflow Soldering: 260 °C for 10 sec.  Hand Soldering: 350 °C for 3 sec.		

#### **Notes:**

- 1. The value are based on 1 die performance
- 2. The products are sensitive to static electricity and care must be fully taken when handling products.



# Electro-Optical Characteristics (Ta=25 $^{\circ}$ C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
		2000	2500			I <sub>F</sub> =20mA*2
Luminous Intensity*1	Iv		7000*3		mcd	I <sub>FP</sub> =100mA*2 (Duty 1/10 @ 400ms)
Viewing Angle*2	$2 heta_{ ext{1/2}}$		120		deg	I <sub>F</sub> =20mA*2
Forward Voltage*2			3.5	4.0		I <sub>F</sub> =20mA*2
	$V_{\mathrm{F}}$		4.3*3		V	I <sub>FP</sub> =100mA* <sub>2</sub> (Duty 1/10 @ 400ms)
Reverse Current*1	$I_R$			50	$\mu$ A	$V_R=5V$

#### **Notes:**

- 1. When three LED dies are operated simultaneously.
- 2. For each die.
- 3. The value only for reference.



# **Reliability Test Items and Conditions**

The reliability of products shall be satisfied with items listed below.

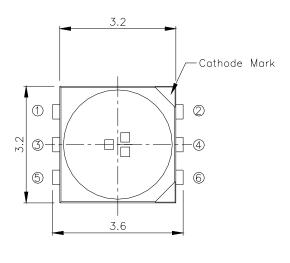
Confidence level: 90%

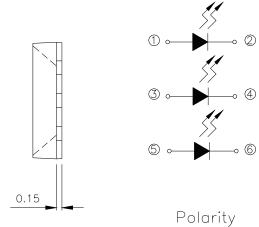
LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260° ℂ T5° ℂ Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H:+100°C 15min  ∫ 5 min  L:-40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H: +100°C 5min $∫ 10  sec$ $L: -10$ °C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°€	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1



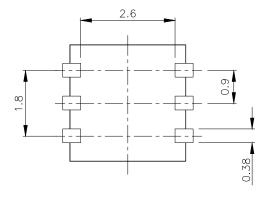
# **Package Outline Dimensions**

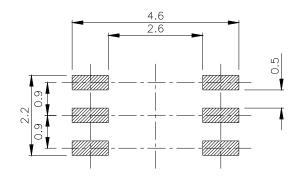












Notes: 1.All dimensions are in millimeters. 2.Tolerances unspecified are ±0.1mm.



# **Color Ranks**

	Rank A0				
X	0.280	0.264	0.283	0.296	
У	0.248	0.267	0.305	0.276	

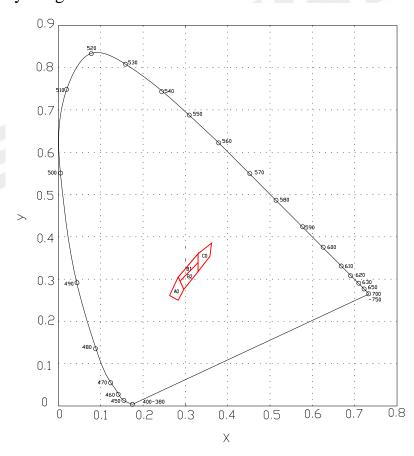
	Rank B1			
X	0.287   0.283   0.330   0.330			
у	0.295	0.305	0.360	0.339

	Rank B2			
X	0.296 0.287 0.330 0.330			
у	0.276	0.295	0.339	0.318

	Rank C0				
X	0.330 0.330 0.361 0.356				
у	0.318	0.360	0.385	0.351	

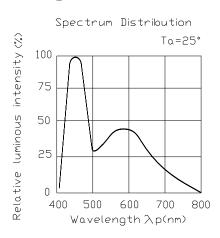
\*The C.I.E. 1931 color rank (Tolerance  $\pm 0.01$ ).

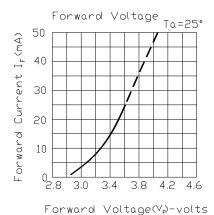
# CIE Chromaticity Diagram

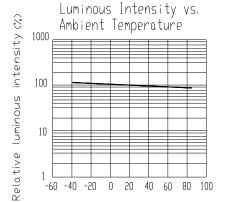




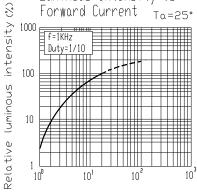
# **Typical Electro-Optical Characteristics Curves**

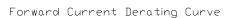




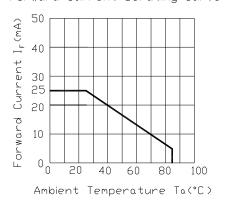




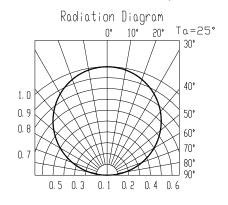




Ambient Temperature Ta(°C)



Forward Current  $I_F(mA)$ 



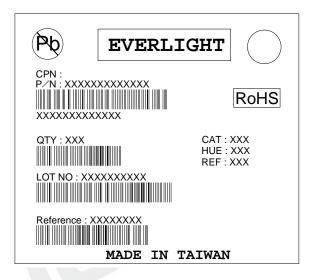


# **Label Explanation**

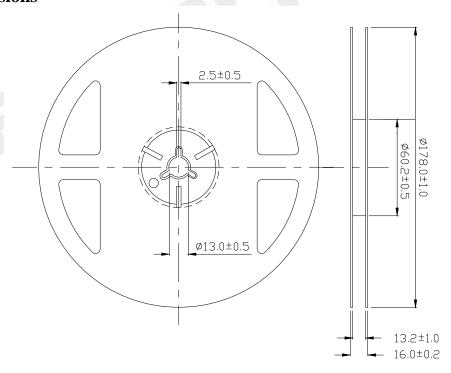
**CAT: Luminous Intensity Rank** 

**HUE: Chromaticity Coordinates** 

**REF: Forward Voltage Rank** 



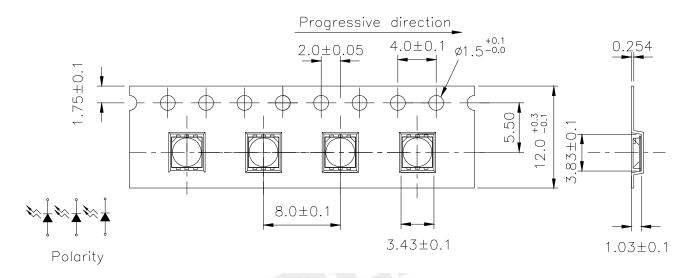
## **Reel Dimensions**



**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm, Unit = mm

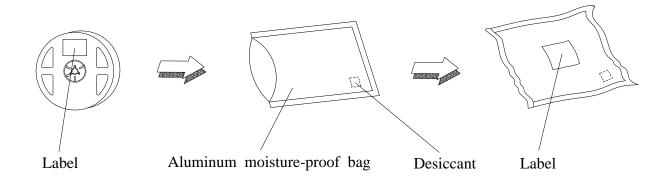


# Carrier Tape Dimensions:Loaded Quantity 2000 pcs Per Reel



**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm, Unit = mm

# **Moisture Resistant Packaging**





## **Precautions for Use**

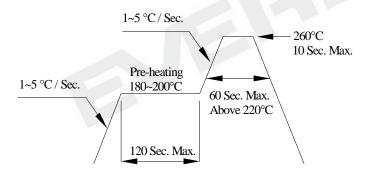
1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen ).

- 2. Storage
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at  $30^{\circ}$ C or less and 90% RH or less.
- 2.3 After opening the package: The LED's floor life are 72 hours under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

- 3. Soldering Condition
  - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
- 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.



### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

